Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)}$ max	I_D max T_A = 25°C
30V	14mΩ @ V_{GS} = 10V	10A
	20mΩ @ V_{GS} = 4.5V	8A

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- **ESD Protected Gate**
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device, Halogan and Antimony Free (Note 2)**
- **Qualified to AEC-Q101 standards for High Reliability**

Description and Applications

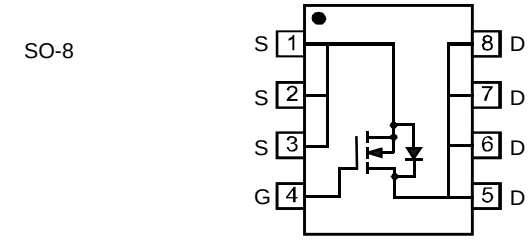
This MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.072 grams (approximate)

SO-8



Top View

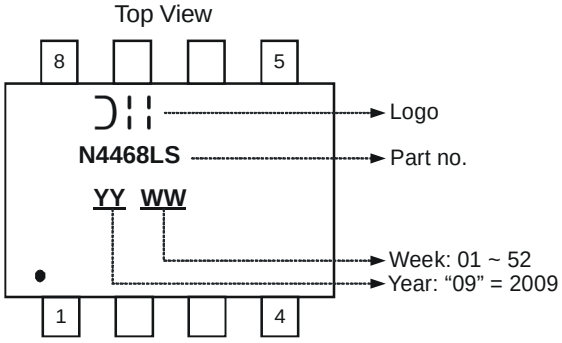
Top View
Internal Schematic

Ordering Information (Note 3)

Part Number	Case	Packaging
DMN4468LSS-13	SO-8	2500 / Tape & Reel

Notes: 1. No purposefully added lead.
2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
3. For packaging details, go to our website at http://www.diodes.com.

Marking Information



Maximum Ratings @T_A = 25℃ unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	30	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current (Note 4)	Steady State	T_A = 25℃ T_A = 70℃	I_D	10 9	A
Pulsed Drain Current (10μs pulse, duty cycle = 1%)			I_{DM}	50	A

Thermal Characteristics

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 4)	P_D	1.52	W
Thermal Resistance, Junction to Ambient (Note 4)	$R_{\theta JA}$	82	℃/W
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta Jc}$	8.2	℃/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	℃

Electrical Characteristics @T_A = 25℃ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	-	-	V	V_{GS} = 0V, I_D = 250μA
Zero Gate Voltage Drain Current T_J = 25℃	I_{DSS}	-	-	1.0	μA	V_{DS} = 30V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	-	-	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	$V_{GS(th)}$	1.05	-	1.95	V	V_{DS} = V_{GS}, I_D = 250μA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	11 15	14 20	mΩ	V_{GS} = 10V, I_D = 11.6A V_{GS} = 4.5V, I_D = 10A
Forward Transfer Admittance	$\|Y_{fs}\|$	-	8	-	S	V_{DS} = 5V, I_D = 11.6A
Diode Forward Voltage	V_{SD}	-	0.73	0.95	V	V_{GS} = 0V, I_S = 1A
DYNAMIC CHARACTERISTICS (Note 6)						
Input Capacitance	C_{iss}	-	867	-	pF	V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	-	85	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	81	-	pF	
Gate Resistance	R_g	-	1.39	-	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge	Q_g	-	18.85	-	nC	V_{GS} = 10V, V_{DS} = 15V, I_D =11.6A
Gate-Source Charge	Q_{gs}	-	2.59	-	nC	
Gate-Drain Charge	Q_{gd}	-	6.15	-	nC	
Turn-On Delay Time	$t_{D(on)}$	-	5.46	-	ns	V_{DD} = 15V, V_{GS} = 10V, R_L = 1.3Ω, R_G = 3Ω, I_D = 1A
Turn-On Rise Time	t_r	-	14.53	-	ns	
Turn-Off Delay Time	$t_{D(off)}$	-	18.84	-	ns	
Turn-Off Fall Time	t_f	-	6.01	-	ns	

Notes: 4. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
5. Short duration pulse test used to minimize self-heating effect.
6. Guaranteed by design. Not subject to product testing.

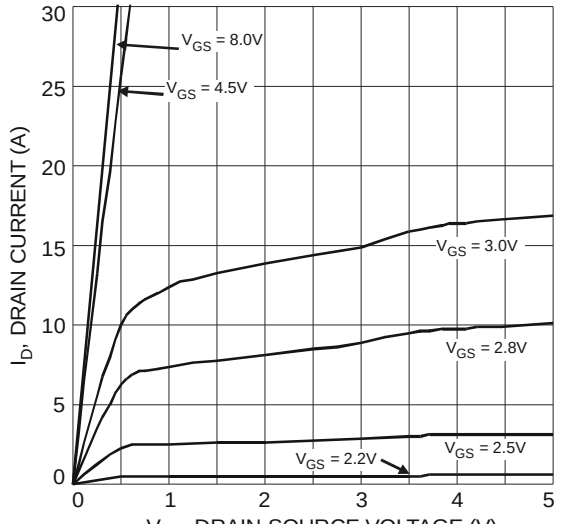


Fig. 1 Typical Output Characteristic

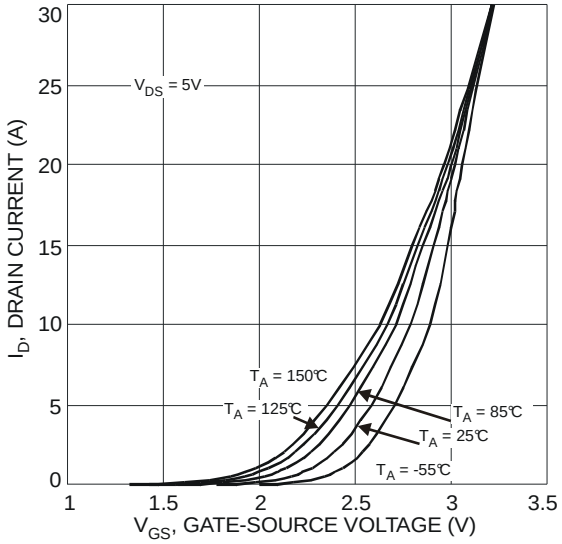


Fig. 2 Typical Transfer Characteristic

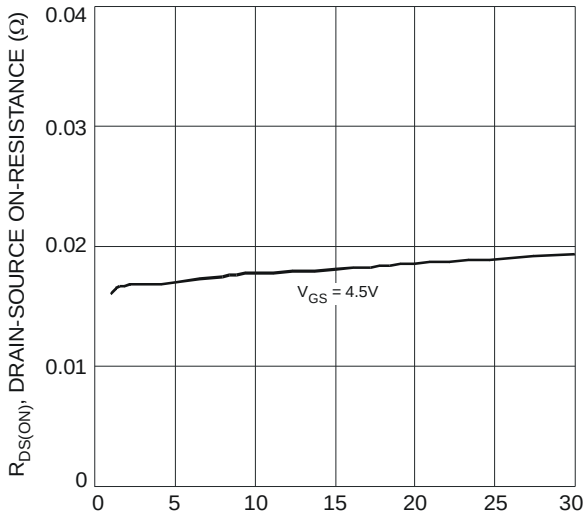


Fig. 3 Typical On-Resistance
vs. Drain Current and Gate Voltage

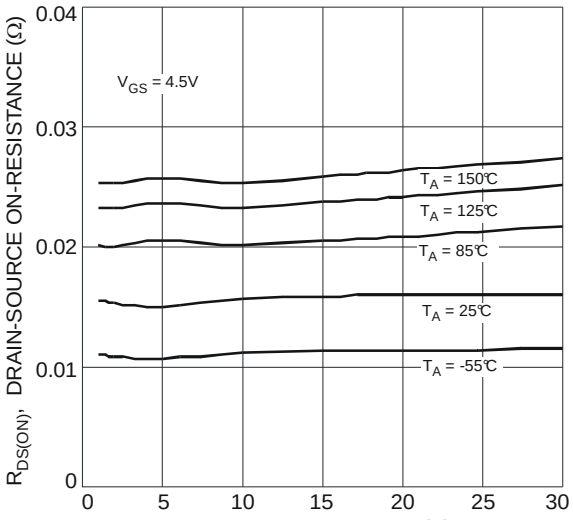


Fig. 4 Typical On-Resistance
vs. Drain Current and Temperature

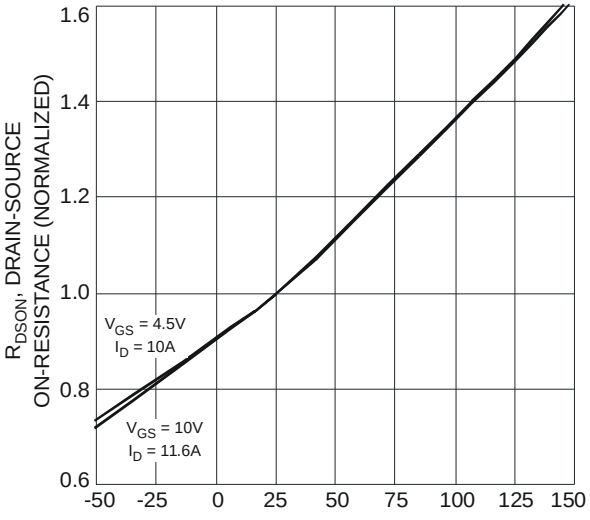


Fig. 5 On-Resistance Variation with Temperature

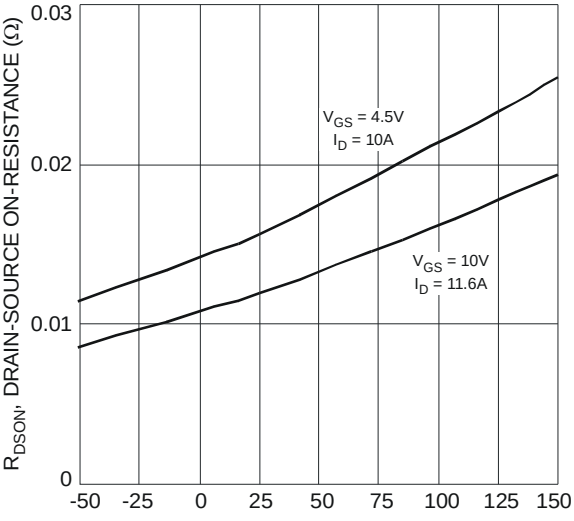


Fig. 6 On-Resistance Variation with Temperature

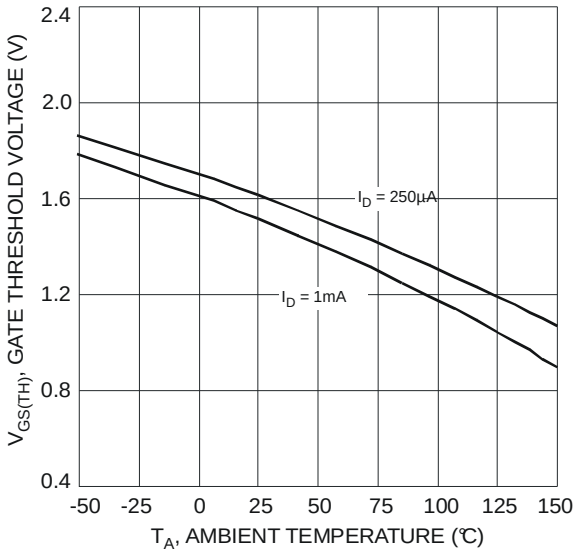


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

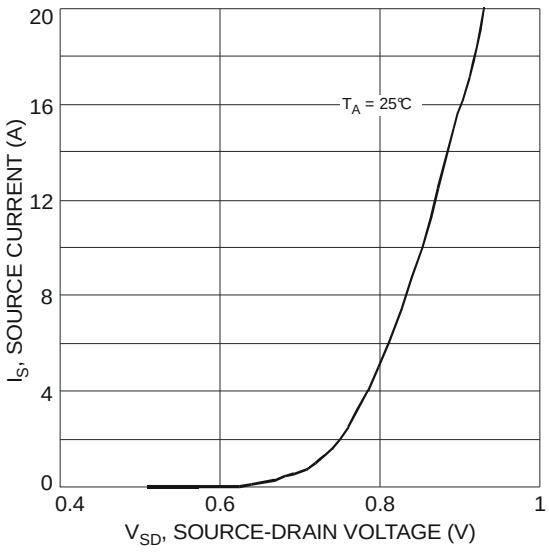


Fig. 8 Diode Forward Voltage vs. Current

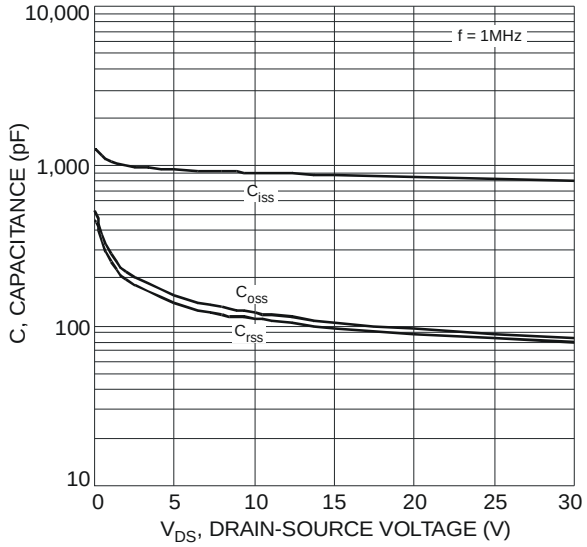


Fig. 9 Typical Total Capacitance

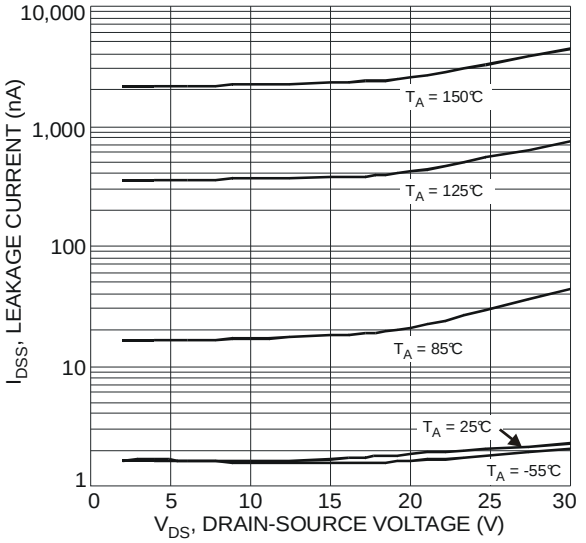


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

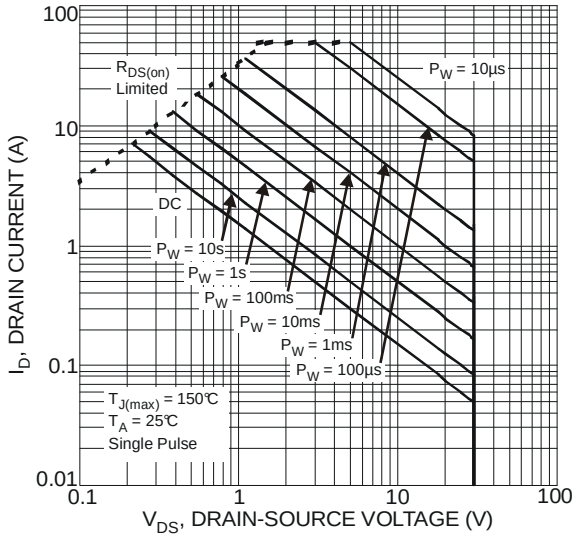


Fig. 11 SOA, Safe Operation Area

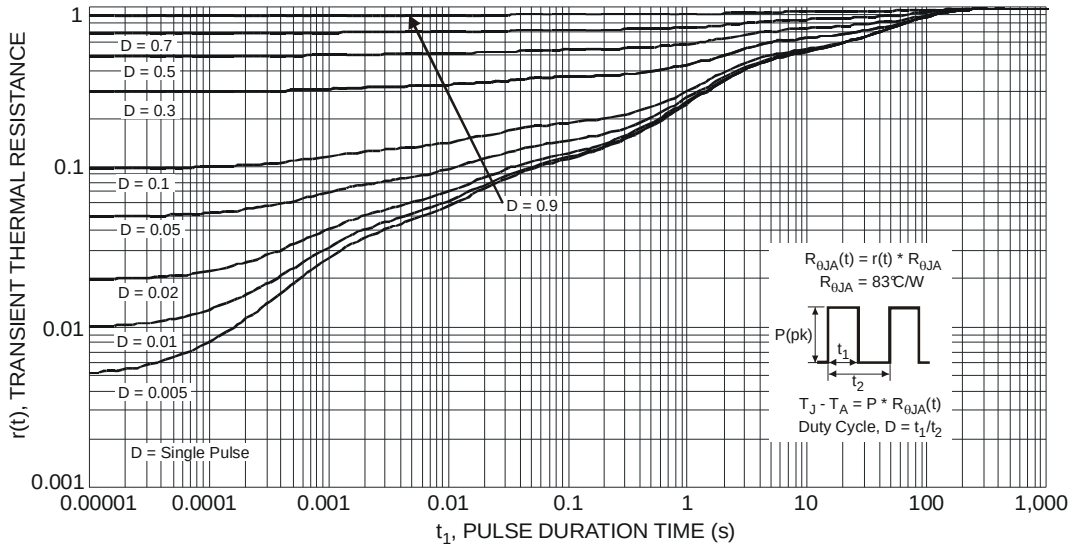
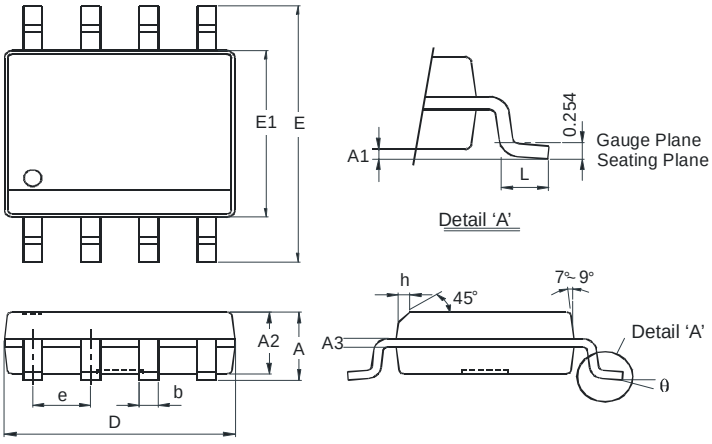


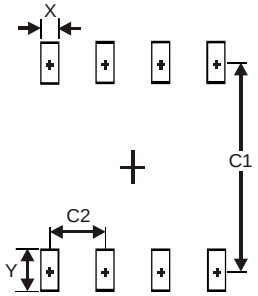
Fig. 12 Transient Thermal Response

Package Outline Dimensions



SO-8		
Dim	**Min**	**Max**
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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